

S3AF THRU S3MF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

Mechanical Data

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz



Simplified outline SMAF and symbol

Pinning

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | Cathode |
| 2 | Anode |

Absolute Maximum Ratings And Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Parameter | Symbols | S3AF | S3BF | S3DF | S3GF | S3JF | S3KF | S3MF | Units |
|--|-----------------------------------|------------|------|------|------|------|------|------|-------|
| Maximum Repetitive Peak Reverse Voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V _{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current at Tc = 125 °C | I _{F(AV)} | 3 | | | | | | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load | I _{FSM} | 80 | | | | | | | A |
| Maximum Forward Voltage at 1 A | V _F | 1.1 | | | | | | | V |
| Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta =125 °C | I _R | 5 125 | | | | | | | μ A |
| Typical Junction Capacitance ⁽¹⁾ | C _j | 32 | | | | | | | pF |
| Typical Thermal Resistance ⁽²⁾ | RθJA | 50 | | | | | | | °C/W |
| | RθJC | 16 | | | | | | | |
| Operating and Storage Temperature Range | T _J , T _{stg} | -55 ~ +150 | | | | | | | °C |

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Rating And Characteristic Curves

Fig.1 Forward Current Derating Curve

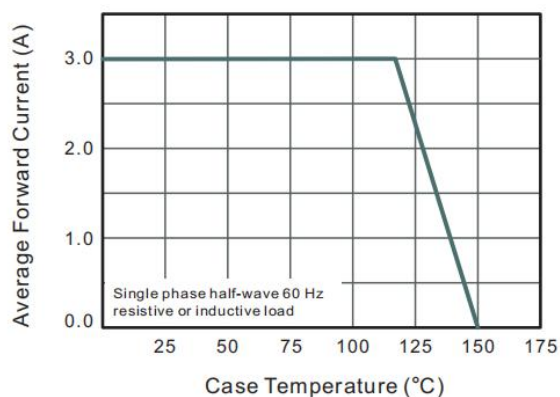


Fig.2 Typical Instantaneous Reverse Characteristics

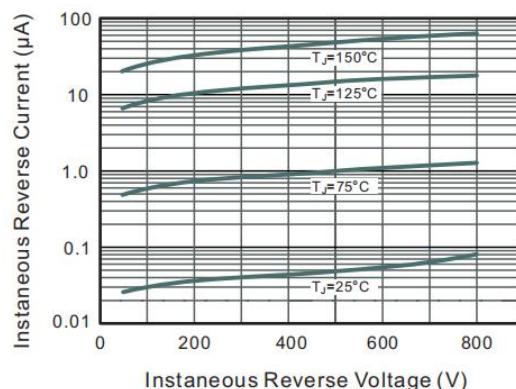


Fig.3 Typical Forward Characteristic

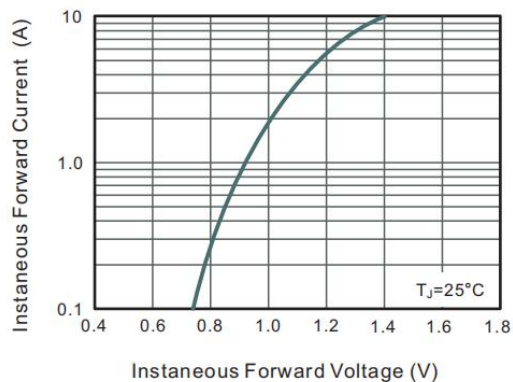


Fig.4 Typical Junction Capacitance

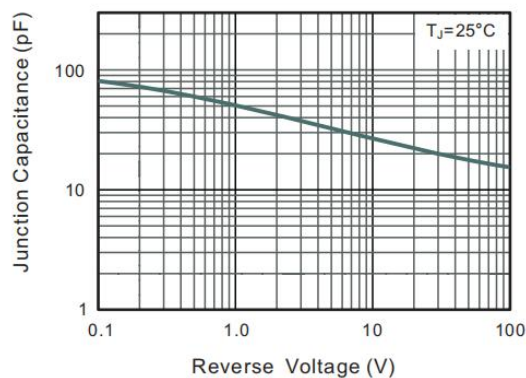
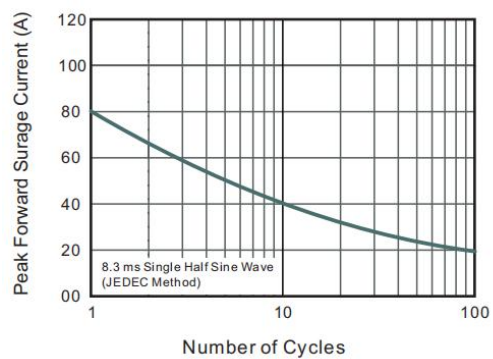


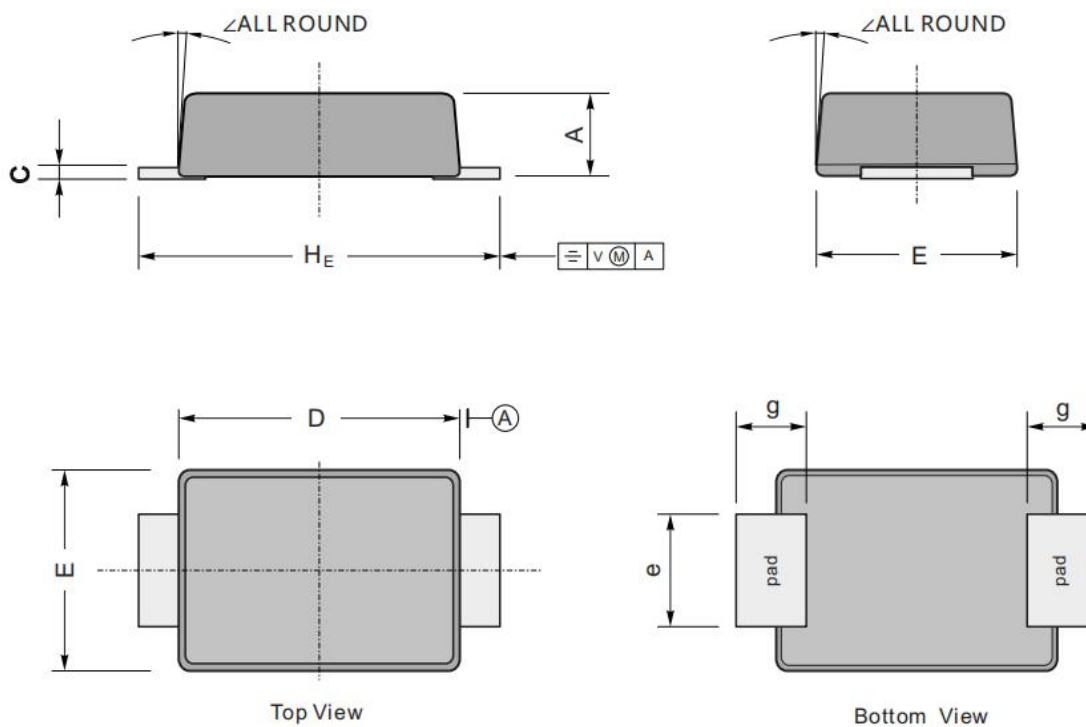
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



Package Outline

Plastic surface mounted package; 2 leads

SMAF



| UNIT | | A | C | D | E | e | g | H _E | ∠ |
|------|-----|-----|------|-----|-----|-----|-----|----------------|----|
| mm | max | 1.2 | 0.20 | 3.7 | 2.7 | 1.6 | 1.2 | 4.9 | 7° |
| | min | 0.9 | 0.12 | 3.3 | 2.4 | 1.3 | 0.8 | 4.4 | |
| mil | max | 47 | 7.9 | 146 | 106 | 63 | 47 | 193 | |
| | min | 35 | 4.7 | 130 | 94 | 51 | 31 | 173 | |

The recommended mounting pad size

